

MH2M32EJ-6,-7,-8/ MH2M32SEJ-6,-7,-8

FAST PAGE MODE 67108864-BIT(2097152-WORD BY 32-BIT)DYNAMIC RAM

DESCRIPTION

The MH2M32EJ/SEJ is 2097152-word × 32-bit dynamic RAM. This consists of sixteen industry standard 1M × 4 dynamic RAMs in SOJ.

The mounting of SOJ on a single in-line package provides any application where high densities and large quantities of memory are required. This is a socket-type memory module, suitable for easy interchange or addition of modules.

FEATURES

Type name	RAS access time (max.ns)	Cycle time (min.ns)	Power dissipation (Typ.mW)	PCB's contacts
MH2M32EJ-6	60	120	3240	Gold plating
MH2M32EJ-7	70	140	2840	
MH2M32EJ-8	80	160	2440	
MH2M32SEJ-6	60	120	3240	Solder plating
MH2M32SEJ-7	70	140	2840	
MH2M32SEJ-8	80	160	2440	

- Utilizes industry standard 1M × 4 RAMs in SOJ
- Single 5V ± 10% supply
- Low stand-by power dissipation
88mW (max) CMOS Input level
- Low operating power dissipation
MH2M32EJ/SEJ-6 4444mW (max)
MH2M32EJ/SEJ-7 3784mW (max)
MH2M32EJ/SEJ-8 3344mW (max)
- All inputs, output TTL compatible and low capacitance
- 1024 refresh cycles every 16.4ms (A₀~A₉)
- 72-pins single in-line package
- Includes decoupling capacitors (0.22 μF × 16)
- Fast page mode capability

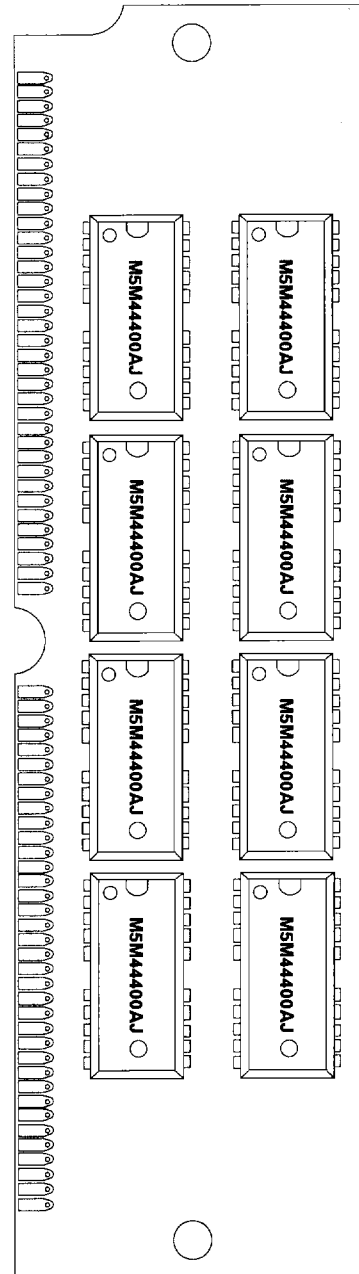
APPLICATION

Main memory unit for computers, Microcomputer memory, Refresh memory for CRT

PIN CONFIGURATION (TOP VIEW) [Both side]

Vss 1
 DQ0 2
 DQ16 3
 DQ1 4
 DQ17 5
 DQ2 6
 DQ18 7
 DQ3 8
 DQ19 9
 VDD 10
 NC 11
 A₀ 12
 A₁ 13
 A₂ 14
 A₃ 15
 A₄ 16
 A₅ 17
 A₆ 18
 NC 19
 DQ4 20
 DQ20 21
 DQ5 22
 DQ21 23
 DQ6 24
 DQ22 25
 DQ7 26
 DQ23 27
 A₇ 28
 NC 29
 VDD 30
 A₈ 31
 A₉ 32
 RAS₃ 33
 RAS₂ 34
 NC 35
 NC 36

 NC 37
 NC 38
 Vss 39
 CAS₀ 40
 CAS₂ 41
 CAS₃ 42
 CAS₁ 43
 RAS₀ 44
 RAS₁ 45
 NC 46
 WE 47
 NC 48
 DQ8 49
 DQ24 50
 DQ9 51
 DQ25 52
 DQ10 53
 DQ26 54
 DQ11 55
 DQ27 56
 DQ12 57
 DQ28 58
 VDD 59
 DQ29 60
 DQ13 61
 DQ30 62
 DQ14 63
 DQ31 64
 DQ15 65
 NC 66
 PD1 67
 PD2 68
 PD3 69
 PD4 70
 NC 71
 Vss 72



	-6	-7	-8
PD1	NC	NC	NC
PD2	NC	NC	NC
PD3	NC	GND	NC
PD4	NC	NC	GND

Outline 72N9J

NC : NO CONNECTION

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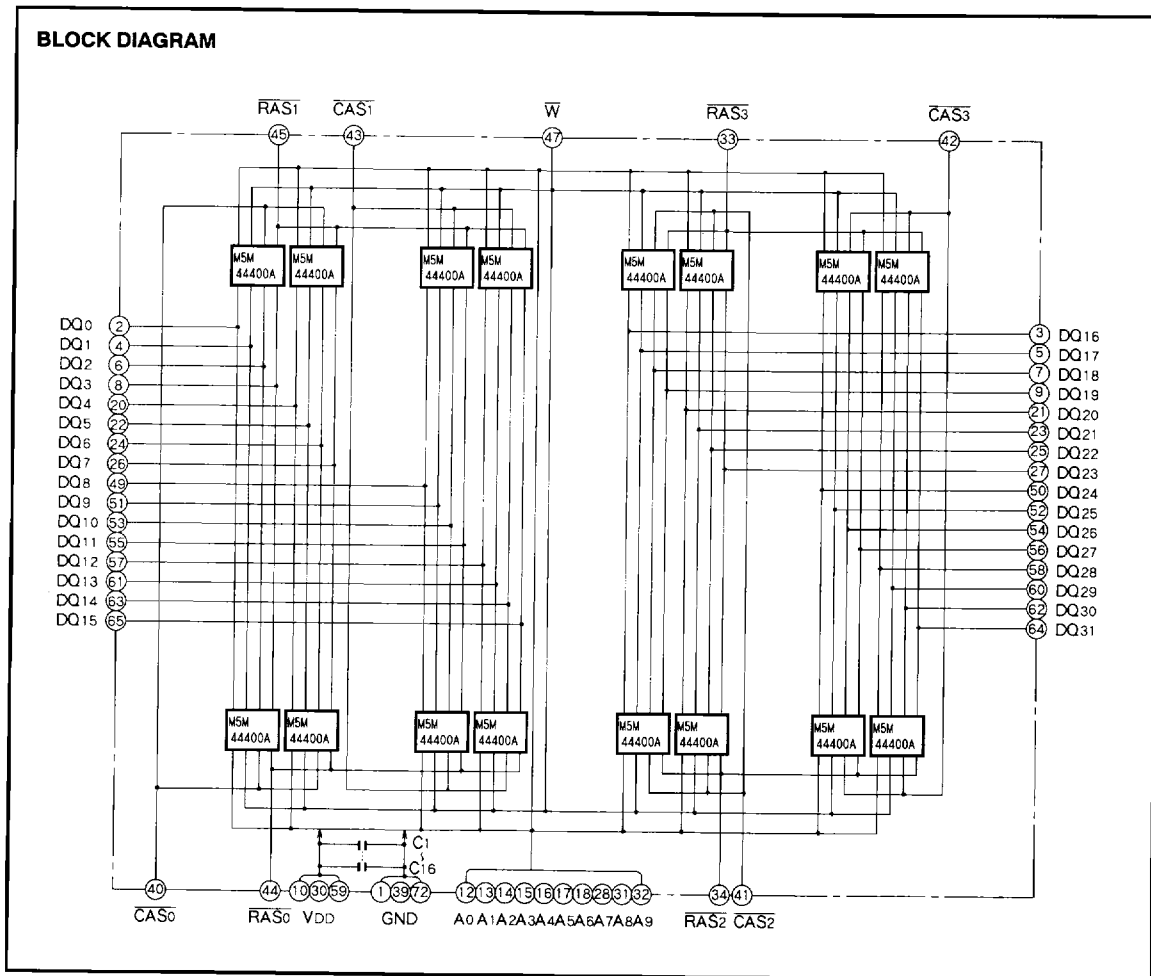
FUNCTION

The MH2M32EJ/SEJ provide, in addition to normal read, and write operations, a number of other functions, e.g., Fast page mode, $\overline{\text{RAS}}$ only refresh. The input conditions for each are shown in Table 1.

Table 1. Input conditions for each mode

Operation	Inputs					Input/Output		Refresh	Remark
	$\overline{\text{RAS}}$	$\overline{\text{CAS}}$	$\overline{\text{W}}$	Row address	Column address	Input	Output		
Read	ACT	ACT	NAC	APD	APD	OPN	VLD	YES	Fast page mode identical
Write (Early write)	ACT	ACT	ACT	APD	APD	VLD	OPN	YES	
$\overline{\text{RAS}}$ only refresh	ACT	NAC	DNC	APD	DNC	DNC	OPN	YES	
Hidden refresh	ACT	ACT	DNC	APD	DNC	OPN	VLD	YES	
CAS before $\overline{\text{RAS}}$ refresh	ACT	ACT	DNC	DNC	DNC	DNC	OPN	YES	
Standby	NAC	DNC	DNC	DNC	DNC	DNC	OPN	NO	

Note. ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, APD : applied, OPN : open



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ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Ratings	Unit
V _{CC}	Supply voltage	With respect to V _{SS}	-1~7	V
V _I	Input voltage		-1~7	V
V _O	Output voltage		-1~7	V
I _O	Output current		50	mA
P _d	Power dissipation	T _a = 25°C	16	W
T _{opr}	Operating temperature		0~70	°C
T _{stg}	Storage temperature		-40~125	°C

RECOMMENDED OPERATING CONDITIONS (T_a = 0~70°C, unless otherwise noted) (Note 1)

Symbol	Parameter	Limits			Unit
		Min	Nom	Max	
V _{CC}	Supply voltage	4.5	5	5.5	V
V _{SS}	Supply voltage	0	0	0	V
V _{IH}	High-level input voltage, all inputs	2.4		6.5	V
V _{IL}	Low-level input voltage, all inputs	-2.0		0.8	V

Note 1 : All voltage values are with respect to V_{SS}.

ELECTRICAL CHARACTERISTICS (T_a = 0~70°C, V_{CC} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted) (Note 2)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
V _{OH}	High-level output voltage	I _{OH} = -5mA	2.4		V _{CC}	V
V _{OL}	Low-level output voltage	I _{OL} = 4.2mA	0		0.4	V
I _{OZ}	Off-state output current	Q floating 0V ≤ V _{OUT} ≤ 5.5V	-20		20	μA
I _I	Input current	0V ≤ V _{IN} ≤ 6.5, Other input pins=0V	-10		10	μA
I _{CC1} (AV)	Average supply current from V _{CC} , operating (Note 3, 4)	MH2M32EJ, SEJ-6	RAS, CAS cycling		816	mA
		MH2M32EJ, SEJ-7	t _{rc} = t _{wc} = min.		696	
		MH2M32EJ, SEJ-8	output open		616	
I _{CC2} (AV)	Supply current from V _{CC} , stand-by (Note 5)	RAS = CAS = V _{IH} , output open		32	mA	
		RAS = CAS ≥ V _{CC} - 0.5, output open		16		
I _{CC3} (AV)	Average supply current from V _{CC} , refreshing (Note 3)	MH2M32EJ, SEJ-6	RAS cycling, CAS = V _{IH}		816	mA
		MH2M32EJ, SEJ-7	t _{rc} = min.		696	
		MH2M32EJ, SEJ-8	output open		616	
I _{CC4} (AV)	Average supply current from V _{CC} Fast-Page-Mode (Note 3, 4)	MH2M32EJ, SEJ-6	RAS = V _{IL} , CAS cycling		816	mA
		MH2M32EJ, SEJ-7	t _{pc} = min.		696	
		MH2M32EJ, SEJ-8	output open		616	
I _{CC6} (AV)	Average supply current from V _{CC} CAS before RAS refresh mode (Note 3)	MH2M32EJ, SEJ-6	CAS before RAS refresh cycling		696	mA
		MH2M32EJ, SEJ-7	t _{rc} = min.		616	
		MH2M32EJ, SEJ-8	output open		536	

Note 2 : Current flowing into an IC is positive, out is negative.

3 : I_{CC1}(AV), I_{CC3}(AV), I_{CC4}(AV) and I_{CC6}(AV) are dependent on cycle rate. Maximum current is measured at the fastest cycle rate.

4 : I_{CC1}(AV) and I_{CC4}(AV) are dependent on output loading. Specified values are obtained with the output open.

CAPACITANCE (T_a = 0~70°C, V_{CC} = 5V ± 10%, V_{SS} = 0V, unless otherwise noted)

Symbol	Parameter	Test conditions	Limits			Unit
			Min	Typ	Max	
C _i (A)	Input capacitance, address inputs	V _i = V _{SS} f = 1MHz V _i = 25mVrms			140	pF
C _i (W)	Input capacitance, write control input				140	pF
C _i (RAS)	Input capacitance, RAS input				70	pF
C _i (CAS)	Input capacitance, CAS input				50	pF
C _o	Output capacitance	V _o = V _{SS} , f = 1MHz, V _i = 25mVrms			25	pF

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SWITCHING CHARACTERISTICS (Ta = 0~70°C, Vcc = 5V ± 10%, Vss = 0V, unless otherwise noted) (Notes 5, 12, 13)

Symbol	Parameter	Limits						Unit
		MH2M32EJ, SEJ-6		MH2M32EJ, SEJ-7		MH2M32EJ, SEJ-8		
		Min	Max	Min	Max	Min	Max	
tCAC	Access time from CAS (Note 6, 7)		15		20		20	ns
tRAC	Access time from RAS (Note 6, 8)		60		70		80	ns
tAA	Column address access time (Note 6, 9)		30		35		40	ns
tCPA	Access time from CAS precharge (Note 6, 10)		35		40		45	ns
tCLZ	Output low impedance time from CAS low (Note 6)	5		5		5		ns
tOFF	Output disable time after CAS high (Note 11)	0	15	0	20	0	20	ns

Note 5: An initial pause of 500 μ s is required after power-up followed by a minimum of eight initialization cycles (any combination of cycles containing a RAS clock such as RAS-only refresh).

Note the RAS may be cycled during the initial pause. And any 8 RAS or RAS/CAS cycles are required after prolonged periods (greater than 16.4ms) of RAS inactivity before proper device operation is achieved.

6: Measured with a load circuit equivalent to 2TTL loads and 100pF.

7: Assumes that $t_{RCD} \geq t_{RCD}(\max)$ and $t_{ASC} \geq t_{ASC}(\max)$.

8: Assumes that $t_{RCD} \leq t_{RCD}(\max)$ and $t_{RAD} \leq t_{RAD}(\max)$. If t_{RCD} or t_{RAD} is greater than the maximum recommended value shown in this table, t_{RAC} will increase by amount that t_{RCD} or t_{RAD} exceeds the value shown.

9: Assumes that $t_{RAD} \geq t_{RAD}(\max)$ and $t_{ASC} \leq t_{ASC}(\max)$.

10: Assumes that $t_{CP} \leq t_{CP}(\max)$ and $t_{ASC} \geq t_{ASC}(\max)$.

11: $t_{OFF}(\max)$ defines the time at which the output achieves the high impedance state ($I_{out} \leq |\pm 10 \mu A|$) and is not reference to $V_{OH}(\min)$ or $V_{OL}(\max)$.

TIMING REQUIREMENTS (For Read, Write, Refresh, and Fast-Page Mode Cycles)

(Ta = 0~70°C, Vcc = 5V ± 10%, Vss = 0V, unless otherwise noted) (Notes 12, 13)

Symbol	Parameter	Limits						Unit
		MH2M32EJ, SEJ-6		MH2M32EJ, SEJ-7		MH2M32EJ, SEJ-8		
		Min	Max	Min	Max	Min	Max	
tREF	Refresh cycle time		16.4		16.4		16.4	ms
tRP	RAS high pulse width	50		60		70		ns
tRCD	Delay time, RAS low to CAS low (Note 14)	20	45	20	50	20	60	ns
tCRP	Delay time, CAS high to RAS low	10		10		10		ns
tRPC	Delay time, RAS high to CAS low	0		0		0		ns
tCPN	CAS high pulse width	10		10		10		ns
tRAD	Column address delay time from RAS low (Note 15)	15	30	15	35	15	40	ns
tASR	Row address setup time before RAS low	0		0		0		ns
tASC	Column address setup time before CAS low (Note 16)	0	10	0	10	0	15	ns
tRAH	Row address hold time after RAS low	10		10		10		ns
tCAH	Column address hold time after CAS low	15		15		15		ns
tT	Transition time (Note 17)	1	50	1	50	1	50	ns

Note 12: The timing requirements are assumed $t_T = 5ns$.

13: $V_{IH}(\min)$ and $V_{IL}(\max)$ are reference levels for measuring timing of input signals.

14: $t_{RCD}(\max)$ is specified as a reference point only. If t_{RCD} is less than $t_{RCD}(\max)$, access time is t_{RAC} . If t_{RCD} is greater than $t_{RCD}(\max)$, access time is controlled exclusively by t_{CAC} or t_{AA} . $t_{RCD}(\min)$ is specified as $t_{RCD}(\min) = t_{RAH}(\min) + 2t_T + t_{ASC}(\min)$.

15: $t_{RAD}(\max)$ is specified as a reference point only. If $t_{RAD} \geq t_{RAD}(\max)$ and $t_{ASC} \leq t_{ASC}(\max)$, access time is controlled exclusively by t_{AA} .

16: $t_{ASC}(\max)$ is specified as a reference point only. If $t_{RCD} \geq t_{RCD}(\max)$ and $t_{ASC} \geq t_{ASC}(\max)$, access time is controlled exclusively by t_{CAC} .

17: t_T is measured between $V_{IH}(\min)$ and $V_{IL}(\max)$.

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Read and Refresh Cycles

Symbol	Parameter	Limits						Unit
		MH2M32EJ, SEJ-6		MH2M32EJ, SEJ-7		MH2M32EJ, SEJ-8		
		Min	Max	Min	Max	Min	Max	
t _{RC}	Read cycle time	120		140		160		ns
t _{RAS}	RAS low pulse width	60	10000	70	10000	80	10000	ns
t _{CAS}	CAS low pulse width	15	10000	20	10000	20	10000	ns
t _{CSH}	CAS hold time after RAS low	60		70		80		ns
t _{RSH}	RAS hold time after CAS low	15		20		20		ns
t _{RCS}	Read setup time before CAS low	0		0		0		ns
t _{RCH}	Read hold time after CAS high (Note 18)	0		0		0		ns
t _{RRH}	Read hold time after RAS high (Note 18)	10		10		10		ns
t _{RAL}	Column address to RAS hold time	30		35		40		ns

Note 18: Either t_{RCH} or t_{RRH} must be satisfied for a read cycle.

Write Cycle (Early Write Cycles)

Symbol	Parameter	Limits						Unit
		MH2M32EJ, SEJ-6		MH2M32EJ, SEJ-7		MH2M32EJ, SEJ-8		
		Min	Max	Min	Max	Min	Max	
t _{WC}	Write cycle time	120		140		160		ns
t _{RAS}	RAS low pulse width	60	10000	70	10000	80	10000	ns
t _{CAS}	CAS low pulse width	15	10000	20	10000	20	10000	ns
t _{CSH}	CAS hold time after RAS low	60		70		80		ns
t _{RSH}	RAS hold time after CAS low	15		20		20		ns
t _{WCS}	Write setup time before CAS low (Note 21)	0		0		0		ns
t _{WP}	Write pulse width	10		15		15		ns
t _{DS}	Data setup time before CAS low or \bar{W} low	0		0		0		ns
t _{DH}	Data hold time after CAS low or \bar{W} low	10		15		15		ns

Fast Page Mode Cycle (Read, Write Cycles) (Note 22)

Symbol	Parameter	Limits						Unit
		MH2M32EJ, SEJ-6		MH2M32EJ, SEJ-7		MH2M32EJ, SEJ-8		
		Min	Max	Min	Max	Min	Max	
t _{PC}	Fast page mode read/write cycle time	40		45		50		ns
t _{RAS}	RAS low pulse width for read write cycle (Note 23)	105	200000	115	200000	130	200000	ns
t _{CP}	CAS high pulse width (Note 24)	10	15	10	20	10	20	ns

Note 22: All previously specified timing requirements and switching characteristics are applicable to their respective fast page mode cycle.

23: t_{RAS}(min) is specified as two cycles of CAS input are performed.

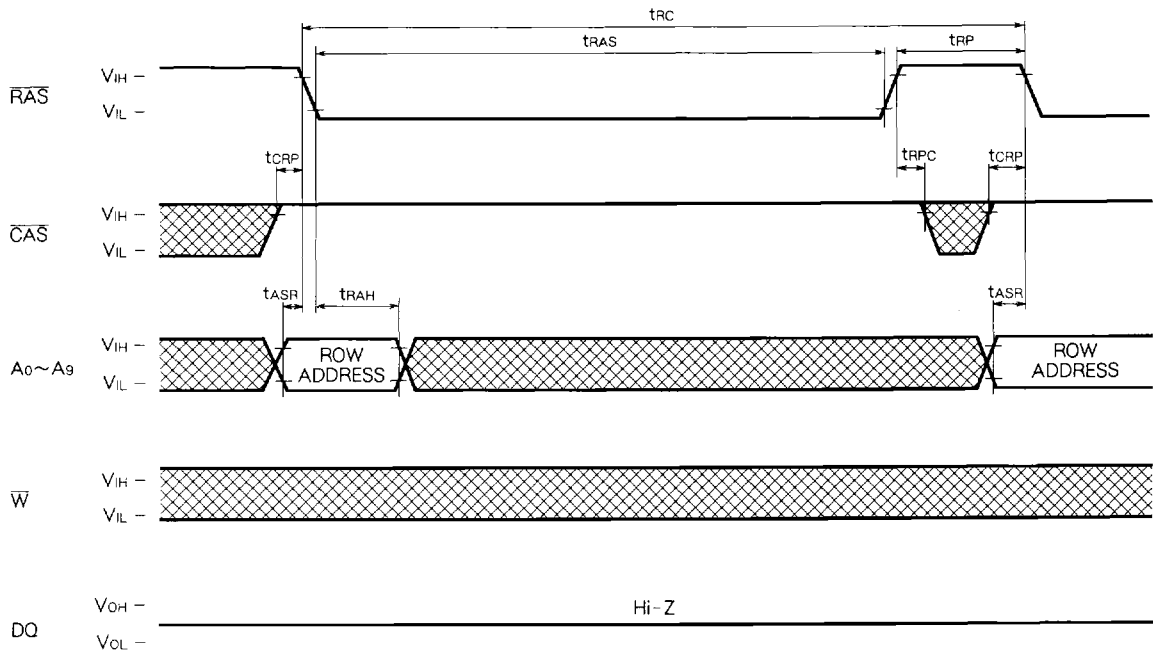
24: t_{CP}(max) is specified as a reference point only.

CAS before RAS Refresh Cycle (Note 25)

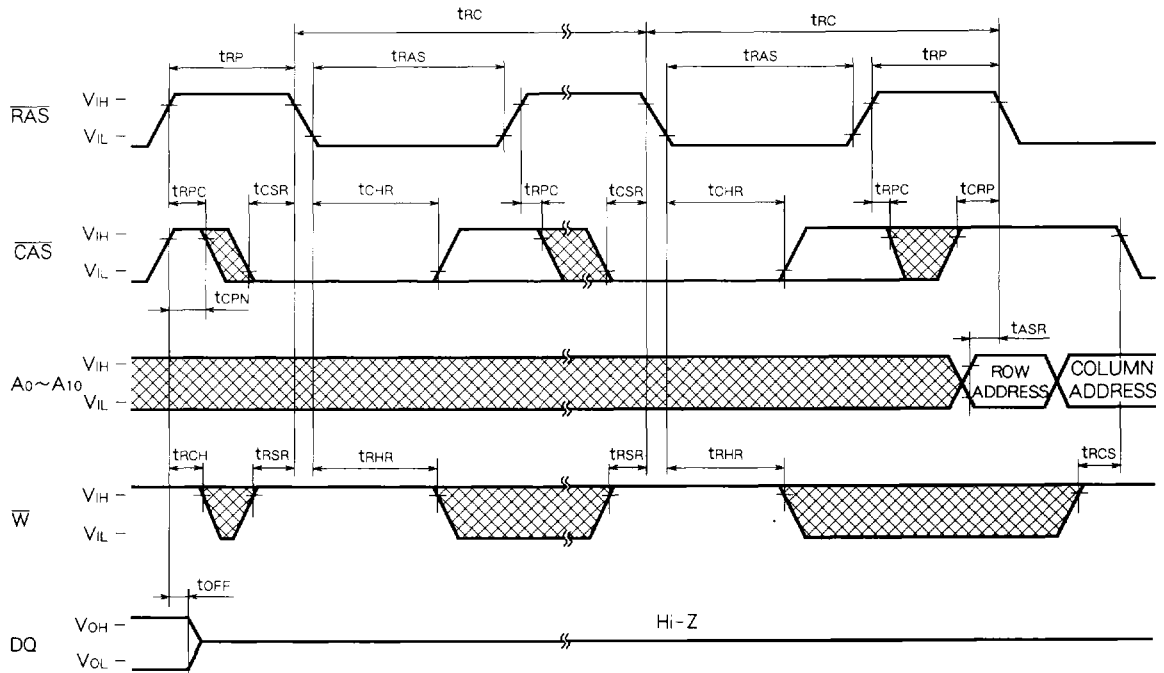
Symbol	Parameter	Limits						Unit
		MH2M32EJ, SEJ-6		MH2M32EJ, SEJ-7		MH2M32EJ, SEJ-8		
		Min	Max	Min	Max	Min	Max	
t _{CSR}	CAS setup time before RAS low	10		10		10		ns
t _{CHR}	CAS hold time after RAS low	10		15		15		ns
t _{RSR}	Read setup time before RAS low	10		10		10		ns
t _{RHR}	Read hold time after RAS low	10		15		15		ns
t _{CAS}	CAS low pulse width	25		30		30		ns

Note 25: Eight or more CAS before RAS cycles instead of eight RAS cycles are necessary for proper operation of CAS before RAS refresh mode.

RAS- only- Refresh Cycle



CAS before RAS Refresh Cycle



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Hidden Refresh Cycle (Read)

